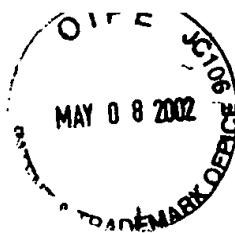


Attorney Docket No.: 042390.P8875



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Xiao-Chun Mu, et al.

Application No: 09/733,289

Filed: December 8, 2000

For: MICROELECTRONIC PACKAGE HAVING
AN INTEGRATED HEAT SINK AND
BUILD-UP LAYERS

Box Non-Fee Amendment
Assistant Commissioner For Patents
Washington, D.C. 20231

Examiner: D. Nguyen

Art Unit: 2814

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26 APRIL 2002
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DEBORAH L. HIGHAM
Name of Person Mailing Correspondence

Deborah O'Hara
Signature Date 4/26/02

AMENDMENT

Dear Sir:

In response to the Office Action mailed April 11, 2002, Applicants elect Claim

Set I, as set forth in the April 11, 2002 Office Action, which includes claims 1-5 and

10-17 without traverse. Applicants elect the species of Embodiment 5, as set forth in the

April 11, 2002 Office Action, which includes figures 20-26. Please charge any shortages

and credit any overcharges to our Deposit Account number 02-2666.

Respectfully submitted,
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN, LLP

Date: April 26, 2002

Paul A. Mendonca
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